APPLICA	BLE STAN	IDARD										
	Operating temperature range Voltage Current		30 V AC / DC range humid		range			-	-10 °C to 50 °C (packed condition)			
RATING					rating or storage idity range		Re	Relative humidity 90%MAX(no				
			0.20 A Appl			cable ca	able		t=0.12±0.02mm, gold	gold plating		
			SPEC	CIFICA	IOIT/	NS						
IT	EM		TEST METHOD				RE	QU	IREMENTS	QT	АТ	
CONSTR	UCTION	•										
General examination		Visually a	nd by measuring instrumer	nt.		According to drawing.				×	×	
Marking		Confirmed visually.				(note 1,2)				×	×	
ELECTRI	CAL CHA	RACTE	RISTICS									
Voltage proof		90 V AC for 1 min.				No flashover or breakdown.				×	×	
nsulation res	sistance	100 V DC.				50 MΩ MIN.				×	×	
Contact resis	stance	AC 20 mV MAX (1KHz), 1 mA.				200 ms	Ω ΜΑΧ.			×	×	
		5				Including FPC bulk resistance (L=8mm)						
MECHAN	IICAL CHA	ARACTE	RISTICS			iricidal	ng i i o bo	iik ic	Sistance (L-onin)			
Vibration	1107 (2 01 17	_	y 10 to 55 Hz, half amplitude	de 0.75 mi	m,	① No	electrical o	disco	ontinuity of 1 us.	×	Τ_	
		for 10 cycles in 3 axial directions.				 No electrical discontinuity of 1 μs. Contact resistance: 200 mΩ MAX. 						
Shock			981 m/s ² , duration of pulse 6 ms at 3 times in 3 both axial directions.			③ No damage, crack and looseness of parts.			×	-		
Mechanical o	peration		10 times insertions and extractions.			① Contact resistance: 200 mΩ MAX.			×	-		
EDC mataratia		NA	l hu annii anhia EDC						and looseness of parts.	1		
FPC retention force			Measured by applicable FPC. (thickness of FPC shall be t=0.12mm			Direction	on of inser	tion:	2.35 N MIN (<i>note 3</i>)	×	_	
		<u> </u>	condition)									
ENVIRO	MENTAL		ACTERISTICS									
Corrosion sa	It mist	Exposed	at 35±2°C, 5% salt water	spray for 9	96 h.	Contac	t resistand	e: 2	00 mΩ MAX.	×	_	
Rapid change of		Temperature -55→+15 to +35→+85→+15 to +35°C			① Contact resistance: 200 mΩ MAX.				×	_		
temperature		Time $30 \rightarrow 2 \text{ to } 3 \rightarrow 30 \rightarrow 2 \text{ to } 3 \text{ min}$ Under 5 cycles.			② Insulation resistance: 50 MΩ MIN.③ No damage, crack and looseness of parts.							
Damp heat		Exposed at 40±2°C,					damago, c	naoi	tana loosonoos of parto.	×	 -	
(steady state	•		numidity 90 to 95 %, 96 h.			① Car	ataat raaiat		200 m O MAY	-		
Damp heat,cyclic		Exposed at -10 to +65°C, Relative humidity 90 to 96 %,			 Contact resistance: 200 mΩ MAX. Insulation resistance: 1 MΩ MIN. 				×	-		
			, total 240 h.				at high hur					
					 Insulation resistance: 50 MΩ MIN. (at dry) 4 No damage, crack and looseness of parts. 							
Dry heat		Exposed	osed at 85±2°C, 96 h.			① Contact resistance: 200 mΩ MAX.				×	—	
Cold			oosed at -55±3°C, 96 h.			② No damage, crack and looseness of parts.				×	_	
Sulphur dioxide			osed at 40±2°C,			Contact resistance: 200 mΩ MAX.				×	† –	
[JIS C 60068-2-42]			elative humidity 80±5%									
Lludronon ou	Inhida		m for 96 h.									
Hydrogen su [JIS		Relative I	at 40±2°C, numidity 80±5% ,							×		
COUNT		10 to 15 ppm for 96 h. ESCRIPTION OF REVISIONS DESIG			NED CHECKED				<u> </u>			
₩ COON	ı Di	ESCRIPTIC	ON OF KEVISIONS	1	DESIG	INED			CHECKED	D/	DATE	
REMARK							APPROV	ED	NF. MIYAZAKI	16 1	11. 26	
							CHECKE	_	YH. MICHIDA		11. 26	
						DESIGNE			HY. YAMAZAKI	1	11. 26	
Unless otherwise specified, re			refer to IEC 60512.			DRAWN		N	KY. KIKUCHI			
·			DF	DRAWING NO. ELC-372596-00			l					
				RT NO. FH64MA-11S-0. 2		64MA-11S-0. 25SH						
HIROSE ELECTRIC CO., LTD.		+							1/2			
	-2-1		LOTAIO GO., LID.	•	CODE	NU.	UL	JOU	4012-0-00	Δ	1/2	

SPECIFICATIONS								
ITEM	TEST METHOD	REQUIREMENTS	QT	АТ				
Solderability	Soldered at solder temperature, 245±3°C for immersion duration, 3±0.3 sec.	A new uniform coating of solder shall cover a minimum of 95% of the surface being immersed.	×	_				
Resistance to soldering heat	1) Reflow soldering: Peak TMP. 250°C MAX. Reflow TMP. over 230°C within 60 sec. Number of allowed reflow cycles 2 times. 2) Soldering irons: TMP. 350±10°C for 5±1 sec.	No deformation of case of excessive looseness of the terminals. (<i>note 4</i>)	×	_				

(note1)

This is a top contact point connector with back flip lock system.

(note2)

Do not close the actuator before inserting FPC even after the connector is mounted onto a PCB.

Closing the actuator without FPC could make the contact gap smaller, which increases the FPC insertion force.

(note3)

Stabilize the FPC to PCB or something fixed, if pull-up or pull-down force is exepected to be applied to the FPC.

There is a case which the FPC retention force doesn't fullfill the specification depending on the FPC specification.

(note4)

Blisters which may be generated on the housing do not affect product performance.

Note QT:Q	ualification Test AT:Assurance Test X:Applicable Test	DRAWIN	NG NO.	ELC-372596-00-00		
HS	SPECIFICATION SHEET	PART NO.	FH64MA-11S-0.25SHW			
11.0	HIROSE ELECTRIC CO., LTD.	CODE NO	CL580	-4612-0-00	Δ	2/2